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THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Patent Application of:

Tai-Chong CHAI *et al.*

Serial No.: 09/497,421

Filed: February 2, 2000

For: LEAD FRAME FOR AN INTEGRATED  
CIRCUIT CHIP (SMALL WINDOW)

Group Art Unit: 2815

Examiner: L. Cruz

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Commissioner for Patents  
Washington, D.C. 20231

Via Facsimile  
703- 746 3902

Sir:

### AMENDMENT

In response to the Office Action of August 27, 2002, please amend the Application as follows:

### IN THE CLAIMS

Please amend claims 1 and 12 as follows:

1. (Amended) A lead frame, for an integrated circuit chip having a frame engaging bottom surface for attachment to the frame by means of a chip attach material, said chip being formed with outer edges having defined dimensions, said frame comprising:
- a unitary apertured frame having a central through aperture therein including a plurality of uniform sidebars each having an upper chip-supporting surface for engaging the bottom of the surface of the chip with the chip attach material therebetween,
- each of said sidebars having an inner edge and an outer edge, said inner edges defining the central aperture,
- said inner and outer edges being uniformly spaced apart defining therebetween a chip-support zone [for the frame] having defined dimensions,

### CERTIFICATE OF TRANSMISSION

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